

Title (en)  
Electroplating method and electroplating apparatus

Title (de)  
Galvanisierungsverfahren- und Vorrichtung

Title (fr)  
Procédé et appareil de dépôt électrolytique

Publication  
**EP 1496142 A3 20060405 (EN)**

Application  
**EP 03257520 A 20031128**

Priority  
JP 2003192500 A 20030704

Abstract (en)  
[origin: EP1496142A2] The present invention provides a plating method and a plating apparatus capable of plating small parts effectively without any deformation. A object product to be plated is put in each accommodating concave portion in a carrier tape including a number of the accommodating concave portions spaced at a specific interval and this carrier tape is passed through a plating apparatus so as to form metallic plating layer on the surface of the object product to be plated.

IPC 8 full level  
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**C25D 17/06** (2013.01 - EP US); **C25D 17/28** (2013.01 - EP US)

Citation (search report)

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- [YA] EP 1205411 A1 20020515 - STECKELBACH WILHELM [DE], et al
- [A] US 3898145 A 19750805 - DAVIS GERALD G, et al
- [A] EP 0501392 A2 19920902 - AMP INC [US]

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DOCDB simple family (publication)  
**EP 1496142 A2 20050112**; **EP 1496142 A3 20060405**; JP 2005023398 A 20050127; US 2005006243 A1 20050113

DOCDB simple family (application)  
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